

**REMARKS**

The Final Office Action dated March 22, 2005 has been received and its contents carefully considered.

Claims 20, 22, 24-29 and 31 are pending in this application. Claims 20, 26 and 28 are independent claims.

In the Action, the Examiner maintains the final rejection of all of the pending claims 20, 22 and 24-29 and 31 under 35 USC §103(a) as being obvious over Bond et al. (U.S. Patent No. 5,642,261). In response, the Applicant is filing a Notice of Appeal of even date herewith.

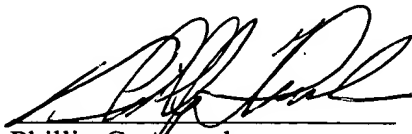
The purpose this Amendment is to present the rejected claims in better form for consideration on appeal. Specifically, claims 26 and 28 are amended to change the phrase "upon application of a heat treatment to the device" to read "upon application of a heat treatment to the device for the purpose of mounting the device to a circuit board." The amendment is intended to make it clear that the recited heat treatment takes place after fabrication of the device is complete, and is not part of the fabrication process itself. Support for the added limitation may be found in the present application, for example, at page 5, lines 4-9.

Accordingly, entry of Amendment pursuant to the 37 CFR §1.116, prior to consideration of the Applicant's appeal, is respectfully requested.

Should the Examiner believe that a conference would be helpful in resolving any questions regarding this Amendment, the Examiner is respectfully invited to call the undersigned attorney to discuss the matter.

Respectfully submitted,

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Date

  
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PGA/

AMENDMENT AFTER FINAL

(09/376,063)